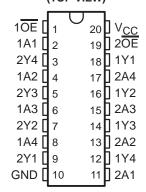
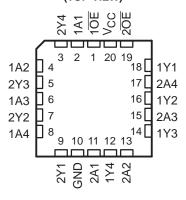
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- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Ceramic (J) DIPs

SN54LVTH240 . . . J PACKAGE SN74LVTH240A . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVTH240 . . . FK PACKAGE (TOP VIEW)



description

These octal buffers and line drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices are organized as two 4-bit buffer/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the devices pass data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH240 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVTH240A is characterized for operation from –40°C to 85°C.



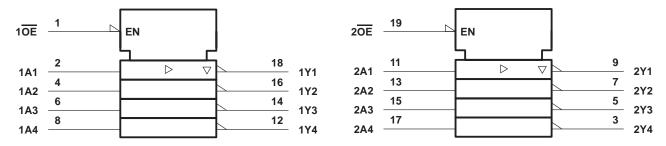
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FUNCTION TABLE (each 4-bit buffer)

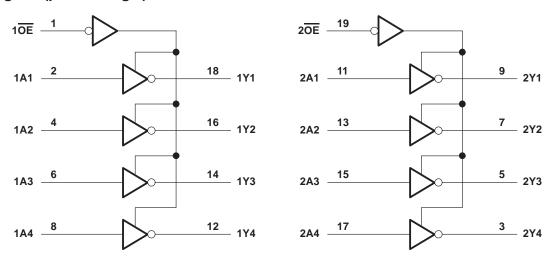
INPU	JTS	OUTPUT				
OE	Α	Υ				
L	Н	L				
L	L	Н				
Н	Χ	Z				

logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)	
Current into any output in the low state, I _O : SN54LVTH240	96 mA
SN74LVTH240A	128 mA
Current into any output in the high state, I _O (see Note 2): SN54LVTH240	48 mA
SN74LVTH240A	
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I_{OK} ($V_O < 0$)	
Package thermal impedance, θ _{JA} (see Note 3): DB package	
DW package	
PW package	
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

		SN54LV	TH240	SN74LVTH240A		UNIT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage	2		2		V	
V _{IL}	Low-level input voltage					0.8	V
VI	Input voltage		5.5		5.5	V	
loн	High-level output current					-32	mA
loL	Low-level output current		48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN5	4LVTH24	0	SN74	UNIT			
				MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII	
VIK	$V_{CC} = 2.7 \text{ V}, \qquad I_{I} = -18 \text{ mA}$		I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0.2			V _{CC} -0.2				
\ \/ .		$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$	2.4			2.4			٧	
VOH		VCC = 3 V	$I_{OH} = -24 \text{ mA}$	2							
		ACC = 2 A	I _{OH} = -32 mA				2			ı	
		V 27V	I _{OL} = 100 μA			0.2			0.2		
		V _{CC} = 2.7 V	I _{OL} = 24 mA			0.5			0.5		
\ \ _{\\\-} .			I _{OL} = 16 mA			0.4			0.4	.,	
VOL			I _{OL} = 32 mA			0.5			0.5	V	
		VCC = 3 V	I _{OL} = 48 mA			0.55					
			I _{OL} = 64 mA						0.55		
		$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10		
١.	Control inputs	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			±1			±1		
11	Data innuta	ta inputs V _{CC} = 3.6 V	VI = VCC			1			1	μΑ	
	Data inputs		V _I = 0			-5			- 5		
loff		V _{CC} = 0, V _I or V _O = 0 to 4.5 V			-				±100	μΑ	
		v _{CC} = 3 V	V _I = 0.8 V	75			75				
I _I (hold)	Data inputs		V _I = 2 V	-75			-75			μΑ	
		$V_{CC} = 3.6 V^{\ddagger}$,	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						±500		
lozh		V _{CC} = 3.6 V,	V _O = 3 V			5			5	μΑ	
lozL		V _{CC} = 3.6 V,	V _O = 0.5 V			- 5			– 5	μΑ	
lozpu		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = 0$	= 0.5 V to 3 V,			±100*			±100	μА	
lozpd		$\frac{V_{CC}}{OE} = 1.5 \text{ V to } 0, V_{O} = 0$	= 0.5 V to 3 V,			±100*			±100	μΑ	
	V _{CC} = 3.6 V,	Outputs high			0.19			0.19			
Icc		$I_{O} = 0$,	Outputs low			5			5	5 mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			0.19			0.19		
ΔICC§	$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$ One input at $V_{CC} - 0.6 \text{ V},$ Other inputs at V_{CC} or GND					0.2			0.2	mA	
Ci	$V_I = 3 \text{ V or } 0$		<u> </u>		3			3		pF	
Co		V _O = 3 V or 0			7			7		pF	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

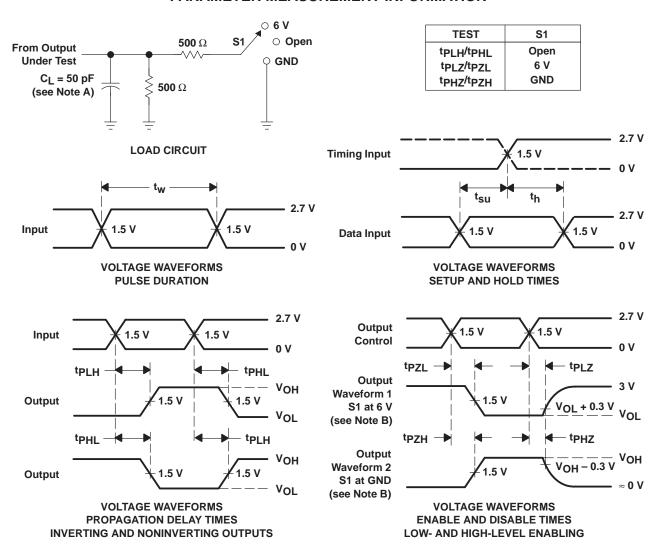
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

		TO (OUTPUT)	SN54LVTH240				SN74LVTH240A					
PARAMETER	FROM (INPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX	
^t PLH	А	~	0.9	4.3		5.1	1.1	2.2	3.8		4.6	ns
t _{PHL}		A	•	1.2	4.7		4.9	1.3	2.6	4		4.2
^t PZH	ŌĒ	~	1	5.7		6.7	1.1	2.6	4.6		5.6	ns
tPZL		•	1.2	5.5		6.2	1.4	2.7	4.4		5	115
^t PHZ	ŌĒ		1	5.1		5.2	2	2.9	4.4		4.6	ns
t _{PLZ}		OE		1.1	5.4		5.4	1.8	3	4.3		4.3

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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